

Notification# 20190513000
Datasheet for TS5A23157
Information Only

Date: May 29, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TS5A23157DGST	null
TS5A23157RSER	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190513000	PCN Date:	May 29, 2019
Title:	Datasheet for TS5A23157		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TS5A23157

SCDS165F –MAY 2004–REVISED JANUARY 2019

Changes from Revision A (October 2018) to Revision B

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• Changed From: 50 To: 63 in Features	1
• Changed From: 300 To: 384 in Features	1
• Changed From: 51 To: 64 in Description	1
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• Changed From: Connect CB1 to VC1 To: Short CB1 to CB0 in CB1 Description in Pin Functions	6
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• Changed $I_{VLDO(LIMIT)}$ into $I_{VLDO(LIMIT)LP}$ and $I_{VLDO(LIMIT)HP}$ in Electrical Characteristics	18
• Changed Figure 1	18
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• Added sentence to Precision References	23
• Changed SYS_FAULT1[POR] to SYS_FAULT1[DRST] in POR (Power On Reset) section	46
• Changed From: 51 devices (1 base device and 50 stack devices) To: 64 devices (1 base device and 63 stack devices) in Communication Interfaces and Programming	49
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• Changed 0x27E OTP_CUST1_STAT1 Factory OTP Reset Value in Register Summary Table From: 0x03 To: 0x01.....	105
• Changed B1 bit value in Register: OTP_CUST1_STAT1 From: 1 To: 0	206
• Changed Figure 43	234
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• Changed From: 50 To: 64 in Application Curves	248
• Changed Figure 59	249
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• Changed Figure 63	253

The datasheet number will be changing.

Device Family	Change From:	Change To:
TS5A23157	SLUSC97A	SLUSC97B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TS5A23157>

Reason for Change:

To reflect the device pin descriptions accurately.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TS5A23157DGSR	TS5A23157DGSRE4	TS5A23157DGSRG4	TS5A23157DGST
TS5A23157RSER			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com